





(0.80 mm) .0315"

POWER/HIGH-SPEED EDGE CARD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-PV

Insulator Material:

Black Liquid Crystal Polymer Signal Contact:

Power Contact: Phosphor Bronze

Plating: Au or Sn over 50 µ" (1.27 µm) Ni Operating Temp: -55 °C to +125 °C RoHS Compliant:

Lead-Free Solderable:

RECOGNITIONS

PROCESSING

For complete scope of recognitions see www.samtec.com/quality

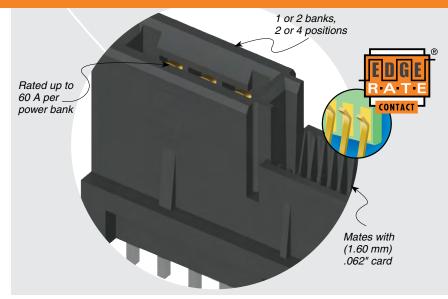


APPLICATION IIIIIIIIIIII

Note: Some lengths, styles and options are non-standard, non-returnable.

Mates with:

(1.60 mm) .062" thick card





20, 30, 40 (Signal positions per row)

(1.60 mm) .062" Thick Card

| 0101141 | POWER POSITIONS | | | | | |
|--------------------|------------------|-----------------|------------------|------------------|-----------|-----------------|
| SIGNAL OSITIONS | A (-2) | B (-2) | C (-2) | A (-4) | B (-4) | C (-4) |
| -20 | (32.10) 1.264 | (15.20) .598 | (18.20) .717 | (44.10) 1.736 | | (18.20) .717 |
| -30 | (40.10) 1.579 | (23.20) .913 | | (52.10) 2.051 | | |
| -40 | (48.10) 1.894 | | (34.20) 1.346 | | | |

= 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail

OPTION

= 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail

-2, -4 (Total, 2 per power bank)

POS

Use with (1.60 mm) .062" Thick PCB

TAIL

OTHER

OPTION

-WT

= Weld

Tab

-2 = Use with (2.36 mm) .093" **Thick PCB**

| < | — A ———→ |
|--|---|
| (12.00) | 00.80) .0315 → B |
| (15.21) | (15.03) |
| $(0.64) \qquad (12.00)$ $SQ \qquad (7.50)$ (7.50) (7.50) | (2.50) (2.50) (-0.098) (-0.098) (-0.044 |

POWER TAIL D (2.35)-1 .093 (3.13)

